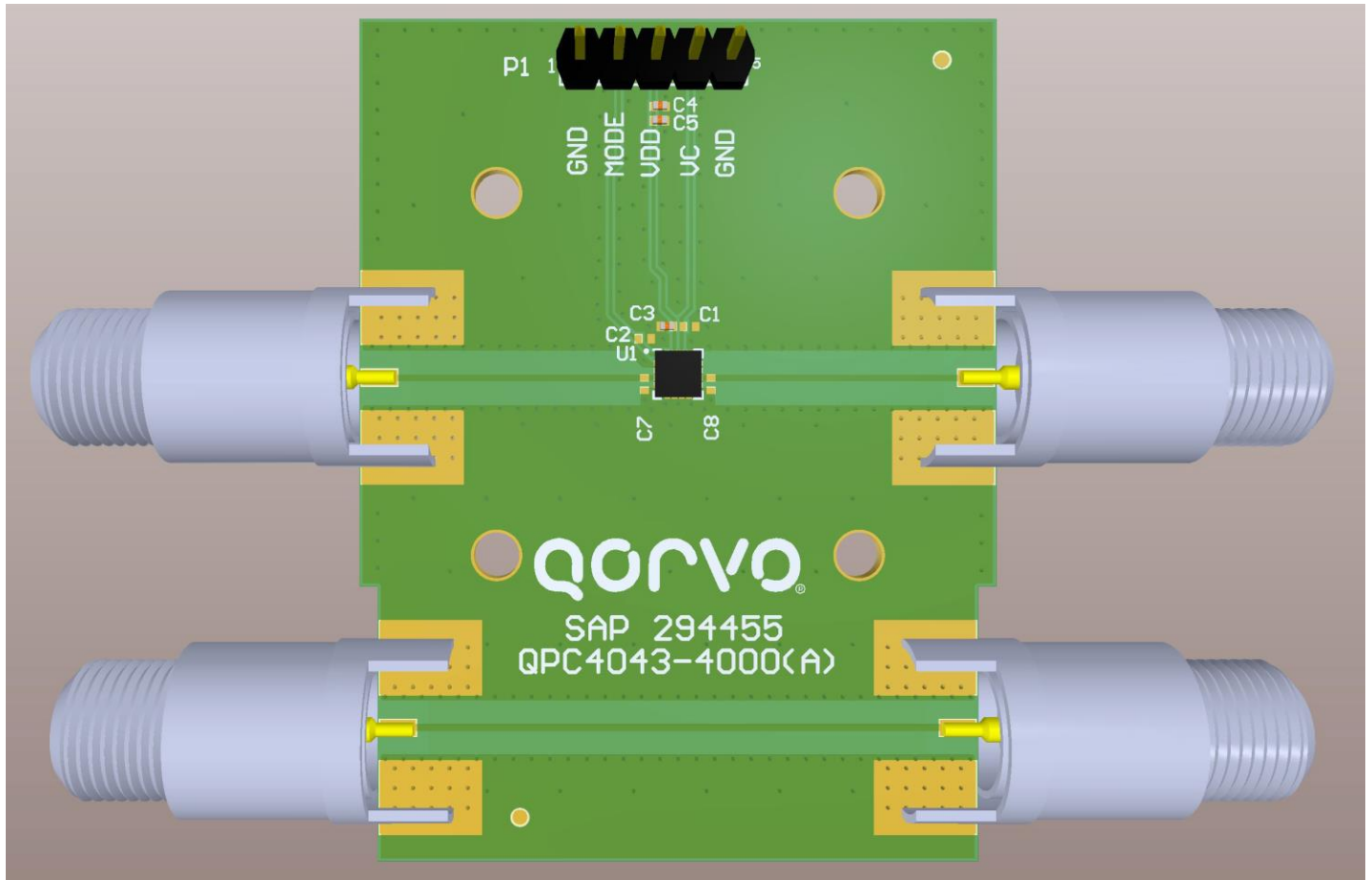
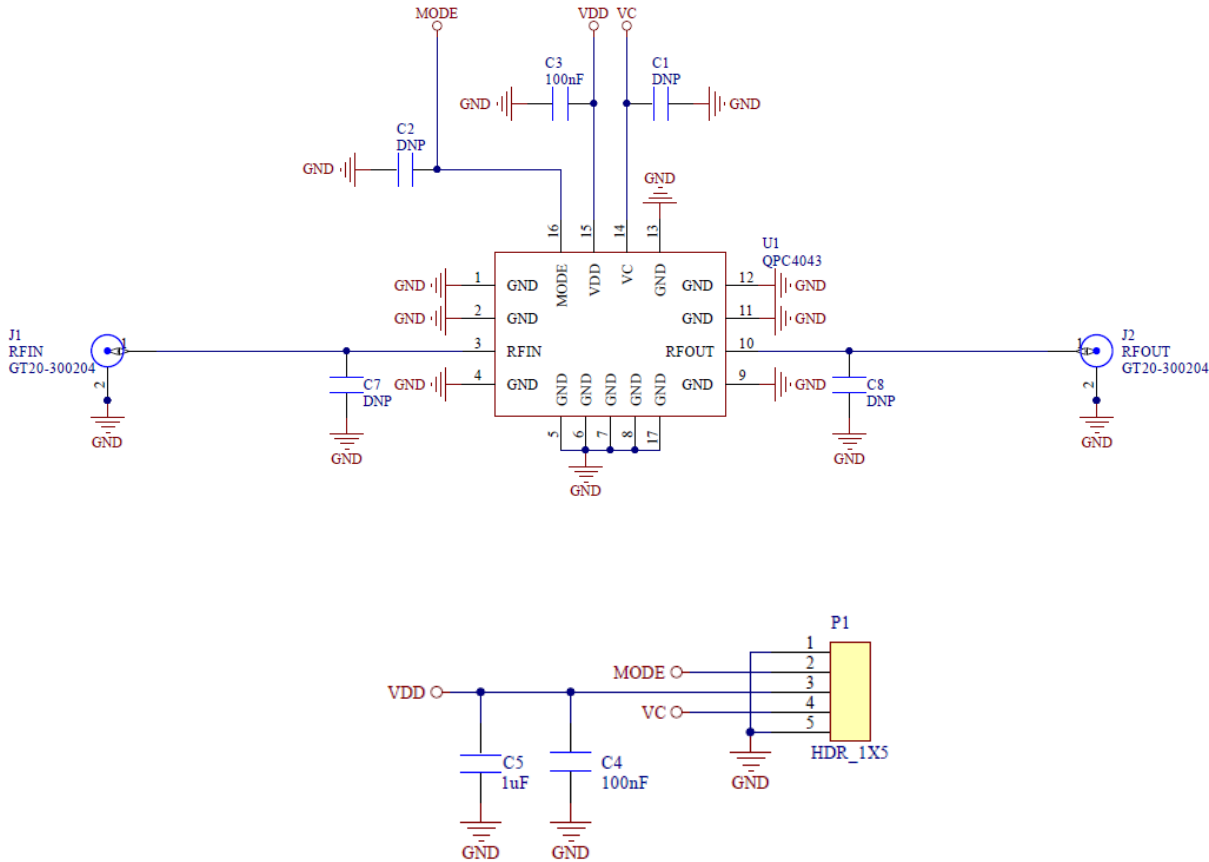


Evaluation Board Assembly Drawing



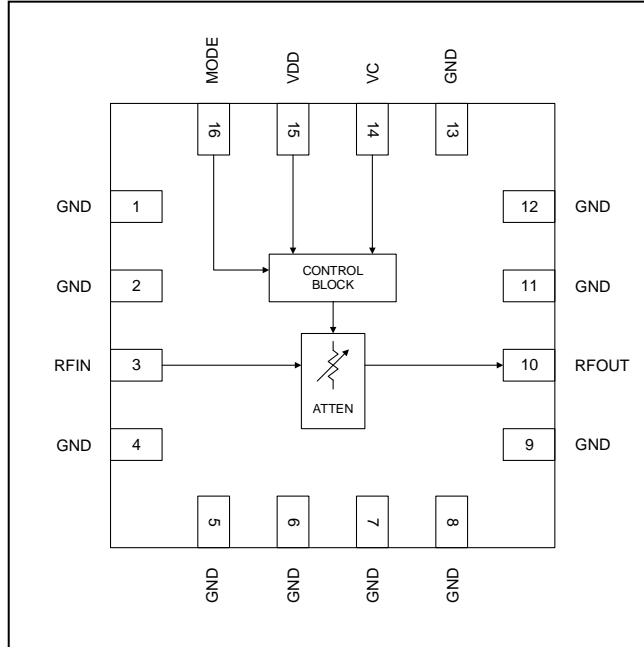
Evaluation Board Schematic; 5 – 3000MHz



Evaluation Board Bill of Materials

Ref Designator	Qty	Description	Manufacturer	Manufacturer Part #
	1	PCB, QPC4043	TTM Technologies, Inc.	QPC4043-4000(A)
C3, C4	2	CAP, 0.1uF, 10%, 16V, X7R, 0402	Kemet	C0402C104K4RACTU
C5	1	CAP, 1uF, 10%, 10V, X7S, 0402	MURATA	GRM155C71A105KE11D
P1	1	CONN, HDR, ST, 5-PIN, T/H	Molex	22-28-4053
J1, J2, J3, J4	4	CONN, F FEM EDGE MOUNT, 75 OHMS, 0.065	Genesis Technology USA	GT20-300204
C1, C2, C7, C8	4	Do Not Populate		

Pin Configuration and Description



Top View

Pin	Label	Description
1	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
2	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
3	RFIN	RF input, use external DC block if external net is not grounded.
4	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
5	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
6	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
7	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
8	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
9	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
10	RFOUT	RF output, use external DC block if external net is not grounded.
11	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
12	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
13	GND	Ground Pin - Pin is not connected internally, recommend connecting to ground
14	VC	Attenuator control voltage
15	VDD	Supply voltage
16	MODE	Attenuation slope control Apply logic LOW to enable negative attenuation slope Apply logic HIGH to enable positive attenuation slope
Pkg Base	GND	Ground connection. The back side of the package should be connected to the ground plane though as short of a connection as possible. PCB vias under the device are recommended.